

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:	Efren M. Lacap et al.		
Application No.:	Unknown	Group No.:	Unknown
Filed:	(Herewith)	Examiner:	Unknown

For: **WAFER-LEVEL CHIP SCALE PACKAGING**

**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

INFORMATION DISCLOSURE STATEMENT TRANSMITTAL
FILED UNDER 37 C.F.R. § 1.97(b)

Pursuant to 37 C.F.R. §§1.56, 1.97(b) and 1.98, Applicants hereby submit an Information Disclosure Statement Form PTO-1449 (modified), along with copies of all references cited therein.

The submission of this IDS is not an admission of prior art. Rather, this IDS fulfills Applicants' duty of disclosure of patents and publications related to the invention pursuant to MPEP 2004: "(T)he question of relevancy in close cases, should be left to the examiner and not the applicant."

Applicants believe no fees are currently due. However, should any fees be required in connection with the filing of this Information Disclosure Statement, the Commissioner is hereby authorized to charge said fees to Deposit Account No. 12-0600.

Respectfully submitted,

Date: August 26, 2003

By Curtis A. Vock
Curtis A. Vock, Reg. No. 38,356
LATHROP & GAGE L.C.
4845 Pearl East Circle, Suite 300
Boulder, Colorado 80301
Tele: (720) 931-3011
Fax: (720) 931-3001